

Summary B.1
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²⁴60. The package of claim ²⁴57, wherein the second surface of the die pad is fully covered with the encapsulant material.

61. The package of claim 57, wherein the package body includes orthogonal exterior side surfaces adjacent to the first exterior surface of the package body, and a severed end of each contact is exposed in a common plane with one of the exterior side surfaces of the package body.

REMARKS

In the Office Action dated December 19, 2000, the Examiner required an election between package, leadframe, and method claims. In response thereto, Applicant has cancelled the pending claims, and added only package claims. Accordingly, the new claims are consistent with the restriction requirement.

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Respectfully submitted,

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